

# CM1451

## LCD and Camera EMI Filter Array with ESD Protection

### Description

The CM1451 is an inductor–capacitor (L–C) based EMI filter array with integrated ESD protection in CSP. The CM1451–06 and CM1451–08 are configured in 6 and 8 channel formats respectively. Each channel is implemented as a 5–pole L–C filter with the component values 9.5 pF – 17 nH – 9.5 pF – 17 nF – 9.5 pF. The CM1451’s roll–off frequency at –10 dB attenuation is 500 MHz. It can be used in applications where the data rates are as high as 200 Mbps while providing greater than 35 dB attenuation over the 800 MHz to 2.7 GHz frequency range. The device has ESD protection diodes on every pin that provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD protection diodes connected to the filter ports safely dissipate ESD strikes of ±15 kV, exceeding the Level 4 requirement of the IEC61000–4–2 international standard. Using the MIL–STD–883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than ±30 kV.

This device is particularly well–suited for portable electronics (e.g. wireless handsets, PDAs) because of its small package format and easy–to–use pin assignments. In particular, the CM1451 is ideal for EMI filtering and protecting data and control lines for the LCD display and camera interface in wireless handsets while maintaining the integrity of signals that have rise/fall times as fast as 2 ns.

The CM1451 incorporates OptiGuard, a coating that results in improved reliability at assembly. The CM1451 is available in a space–saving, low–profile Chip Scale Package with RoHS compliant lead–free finishing.

### Features

- High Bandwidth, High RF Rejection Filter Array
- Six and Eight Channels of EMI Filtering
- Utilizes Inductor–Based Design Technology for True L–C Filter Implementation
- OptiGuard Coating for Improved Reliability
- Chip Scale Package (CSP) Features Extremely Low Lead Inductance for Optimum Filter and ESD Performance
- 15 kV ESD Protection on Each Channel (IEC 61000–4–2 Level 4, Contact Discharge)
- 30 kV ESD Protection on Each Channel (HBM)
- Better than 40 dB of Attenuation at 1 GHz
- Maintains Signal Integrity for Signals that Have a Risetime and Faltime as Fast as 2 ns

### Applications

- LCD and Camera Data Lines in Mobile Handsets
- I/O Port Protection for Mobile Handsets, Notebook Computers, PDAs, etc.
- Wireless Handsets / Cell Phones



ON Semiconductor®

<http://onsemi.com>

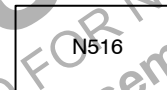


WLCSP15  
CP SUFFIX  
CASE 567BT

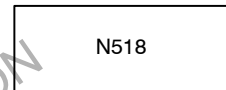


WLCSP20  
CP SUFFIX  
CASE 567CL

### MARKING DIAGRAM



N516



N518

CM1451–06  
15–Bump CSP Package

CM1451–08  
20–Bump CSP Package

N516 = CM1451–06CP

N518 = CM1451–08CP

### ORDERING INFORMATION

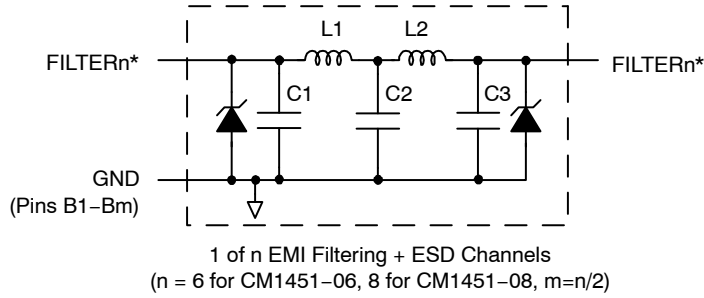
Device	Package	Shipping†
CM1451–06CP	CSP–15 (Pb–Free)	3500/Tape & Reel
CM1451–08CP	CSP–20 (Pb–Free)	3500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

- 15–Bump, 3.006 mm x 1.376 mm Footprint Chip Scale Package (CM1451–06CP)
- 20–Bump, 4.006 mm x 1.376 mm Footprint Chip Scale Package (CM1451–08CP)
- These Devices are Pb–Free and are RoHS Compliant
- EMI Filtering for Data Ports in Cell Phones, PDAs or Notebook Computers
- Handheld PCs / PDAs
- LCD and Camera Modules

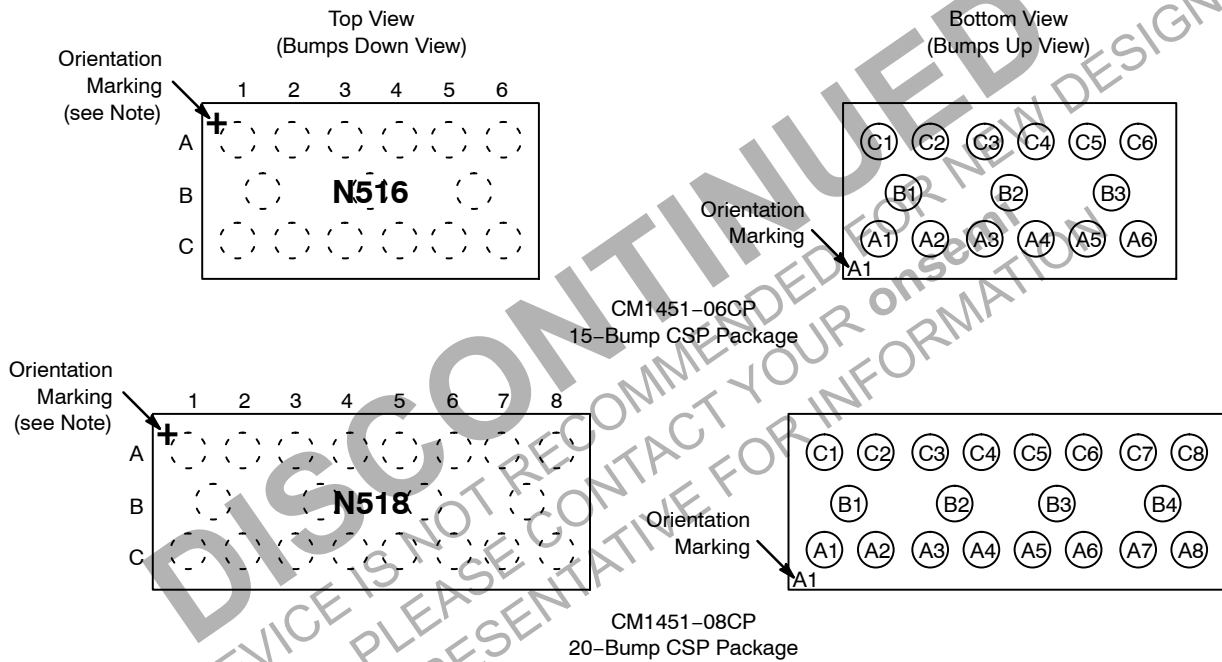
# CM1451

## BLOCK DIAGRAM



\*See Package/Pinout Diagrams for expanded pin information.

## PACKAGE / PINOUT DIAGRAMS



Note: Lead-free devices are specified by using a "+" character for the top side orientation mark.

Table 1. PIN DESCRIPTIONS

CM1451-06	CM1451-08	Name	Description	CM1451-06	CM1451-08	Name	Description
Pin(s)	Pin(s)			Pin(s)	Pin(s)		
A1	A1	FILTER1	Filter Channel 1	C1	C1	FILTER1	Filter Channel 1
A2	A2	FILTER2	Filter Channel 2	C2	C2	FILTER2	Filter Channel 2
A3	A3	FILTER3	Filter Channel 3	C3	C3	FILTER3	Filter Channel 3
A4	A4	FILTER4	Filter Channel 4	C4	C4	FILTER4	Filter Channel 4
A5	A5	FILTER5	Filter Channel 5	C5	C5	FILTER5	Filter Channel 5
A6	A6	FILTER6	Filter Channel 6	C6	C6	FILTER6	Filter Channel 6
-	A7	FILTER7	Filter Channel 7	-	C7	FILTER7	Filter Channel 7
-	A8	FILTER8	Filter Channel 8	-	C8	FILTER8	Filter Channel 8
B1-B3	B1-B4	GND	Device Ground				

# CM1451

## SPECIFICATIONS

**Table 2. ABSOLUTE MAXIMUM RATINGS**

Parameter	Rating	Units
Storage Temperature Range	-65 to +150	°C
Current per Inductor	30	mA
DC Package Power Rating	500	mW

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

**Table 3. STANDARD OPERATING CONDITIONS**

Parameter	Rating	Units
Operating Temperature Range	-40 to +85	°C

**Table 4. ELECTRICAL OPERATING CHARACTERISTICS** (Note 1)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$L_{TOT}$	Total Channel Inductance ( $L_1 + L_2$ )			34		nH
$L_1, L_2$	Inductance			17		nH
$R_{DC\ IN-OUT}$	DC Channel Resistance			18		$\Omega$
$C_{TOT}$	Total Channel Capacitance ( $C_1 + C_2 + C_3$ )	At 2.5 V DC, 1 MHz, 30 mV AC	22.8	28.5	34.2	pF
$C_1, C_2, C_3$	Capacitance	At 2.5 V DC, 1 MHz, 30 mV AC	7.6	9.5	11.4	pF
$f_C$	Cut-off Frequency $Z_{SOURCE} = 50\ \Omega, Z_{LOAD} = 50\ \Omega$			260		MHz
$f_{RO}$	Roll-off Frequency at -10 dB Attenuation $Z_{SOURCE} = 50\ \Omega, Z_{LOAD} = 50\ \Omega$			500		MHz
$V_{DIODE}$	Diode Standoff Voltage	$I_{DIODE} = 10\ \mu A$		6.0		V
$I_{LEAK}$	Diode Leakage Current	$V_{DIODE} = +3.3\ V$		0.1	1.0	$\mu A$
$V_{SIG}$	Signal Clamp Voltage Positive Clamp Negative Clamp	$I_{LOAD} = 10\ mA$	5.6 -1.5	6.8 -0.8	9.0 -0.4	V
$V_{ESD}$	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4	(Note 2)	30 15			kV
$R_{DYN}$	Dynamic Resistance Positive Negative			2.30 0.90		$\Omega$

- $T_A = 25^\circ C$  unless otherwise specified.
- ESD applied to input and output pins with respect to GND, one at a time.

# CM1451

## PERFORMANCE INFORMATION

Typical Filter Performance ( $T_A = 25^\circ\text{C}$ , DC Bias = 0 V, 50  $\Omega$  Environment)

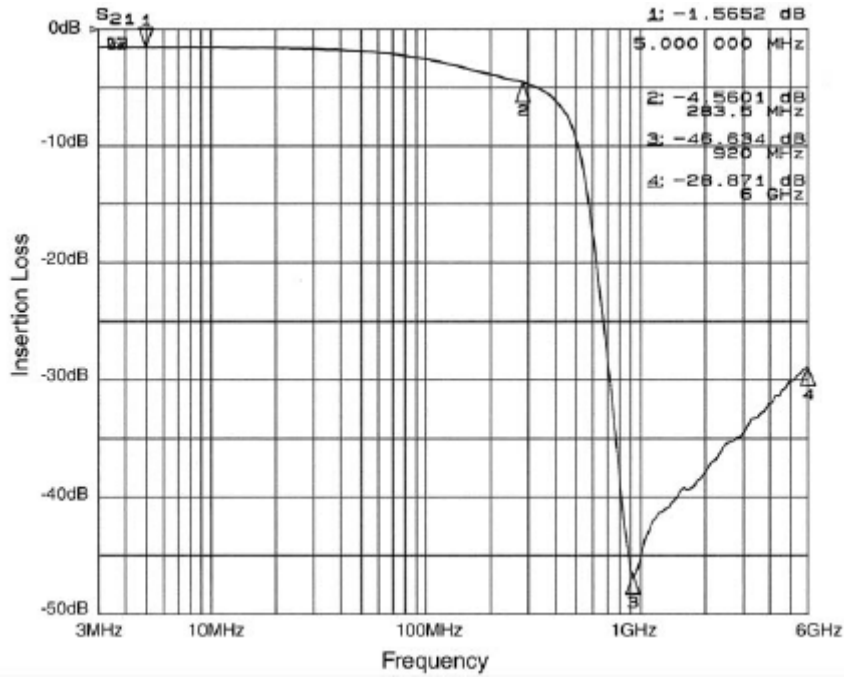


Figure 1. Insertion Loss vs. Frequency (A1-C1 to GND B1)

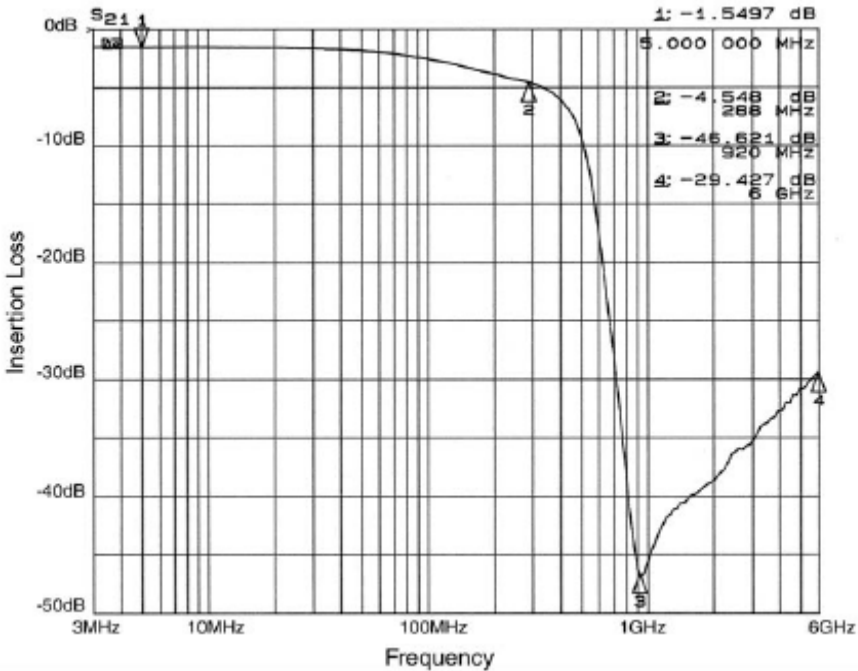


Figure 2. Insertion Loss vs. Frequency (A2-C2 to GND B1)

# CM1451

## PERFORMANCE INFORMATION (Cont'd)

Typical Filter Performance ( $T_A = 25^\circ\text{C}$ , DC Bias = 0 V, 50  $\Omega$  Environment)

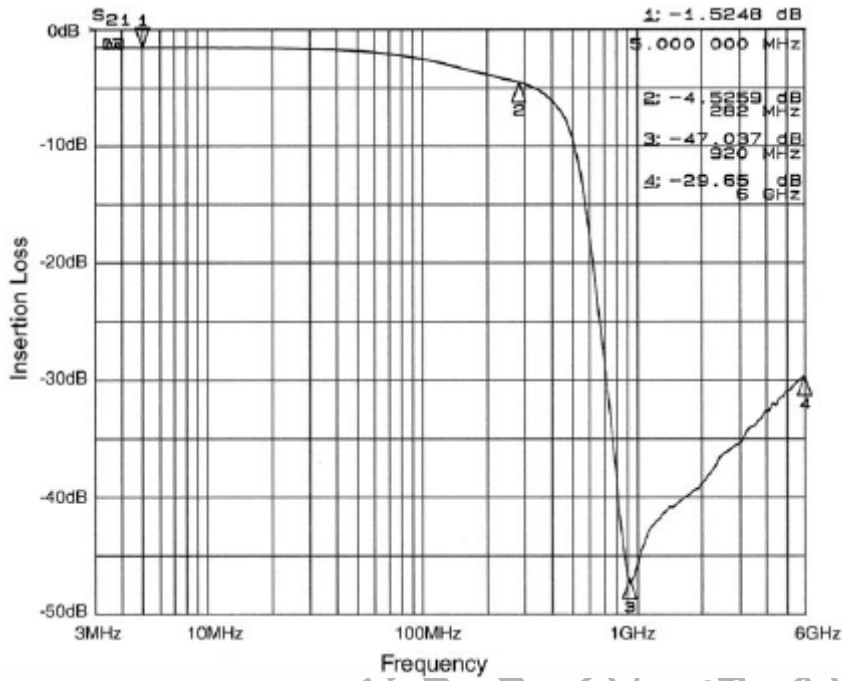


Figure 3. Insertion Loss vs. Frequency (A3-C3 to GND B2)

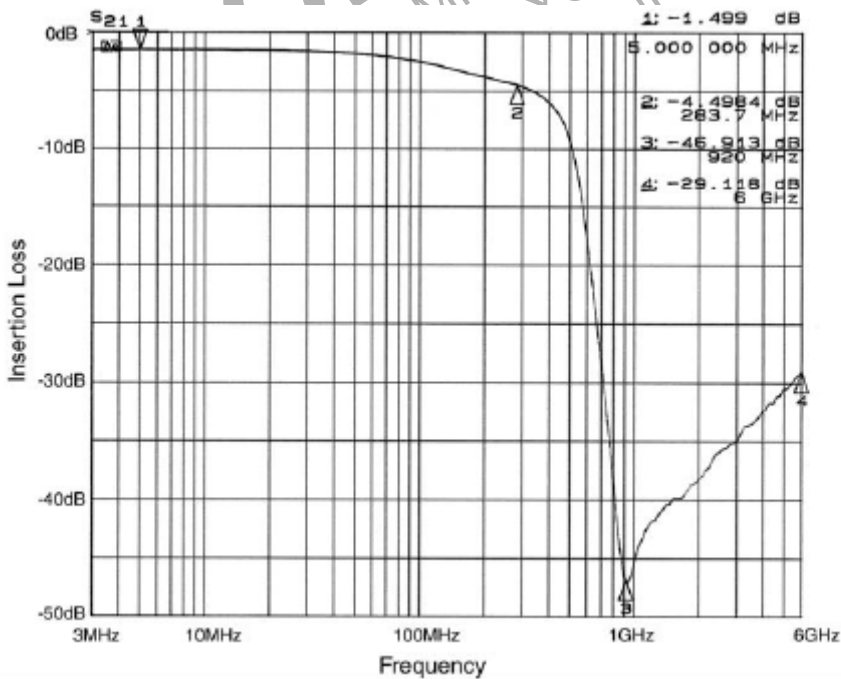


Figure 4. Insertion Loss vs. Frequency (A4-C4 to GND B2)

# CM1451

## PERFORMANCE INFORMATION (Cont'd)

Typical Filter Performance ( $T_A = 25^\circ\text{C}$ , DC Bias = 0 V, 50  $\Omega$  Environment)

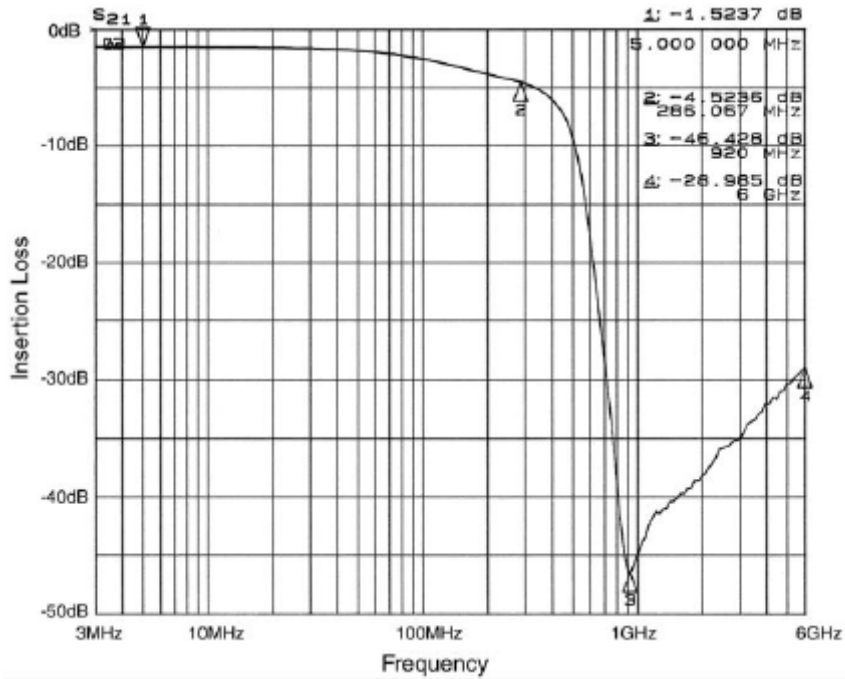


Figure 5. Insertion Loss vs. Frequency (A5-C5 to GND B3)

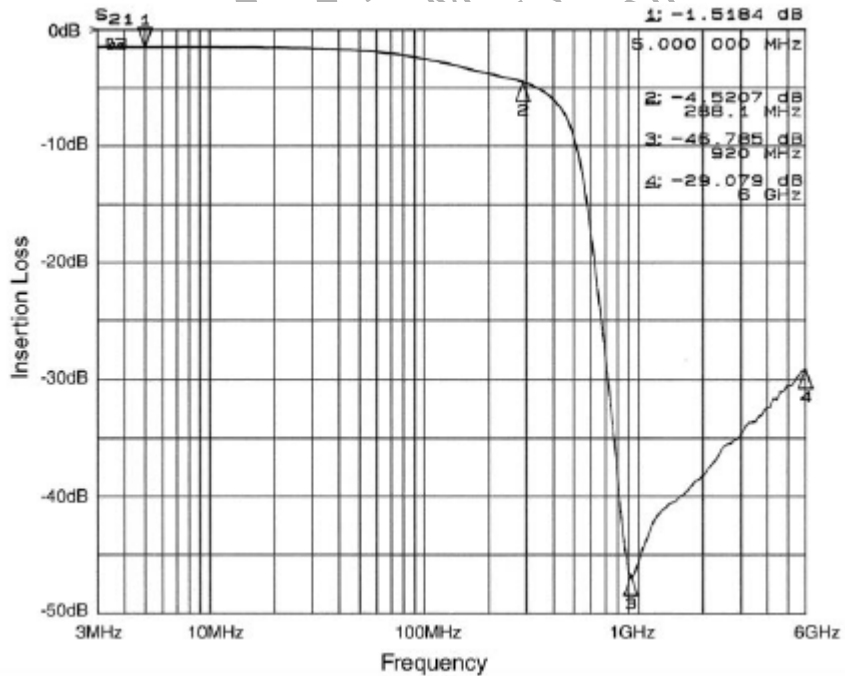


Figure 6. Insertion Loss vs. Frequency (A6-C6 to GND B3)

PERFORMANCE INFORMATION (Cont'd)

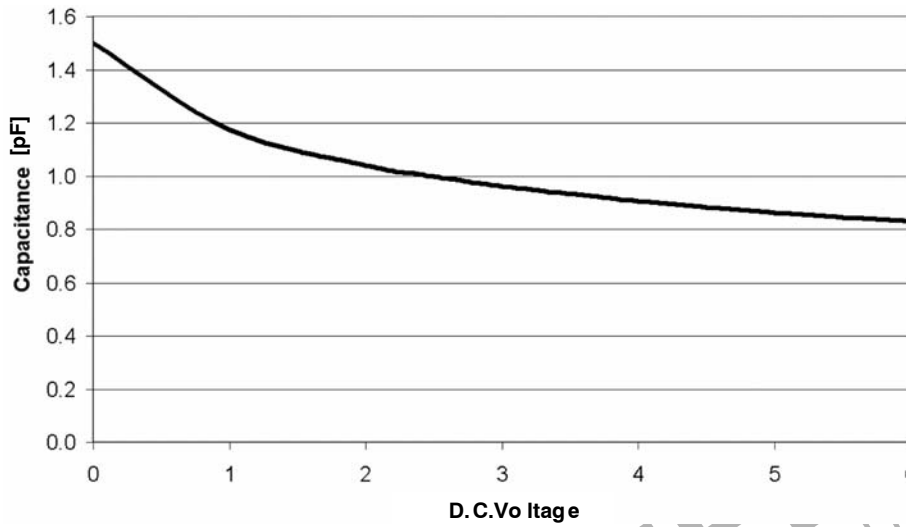


Figure 7. Filter Capacitance vs. Input Voltage over Temperature (normalized to capacitance at 2.5 VDC and 25°C)

Transient Response Characteristics

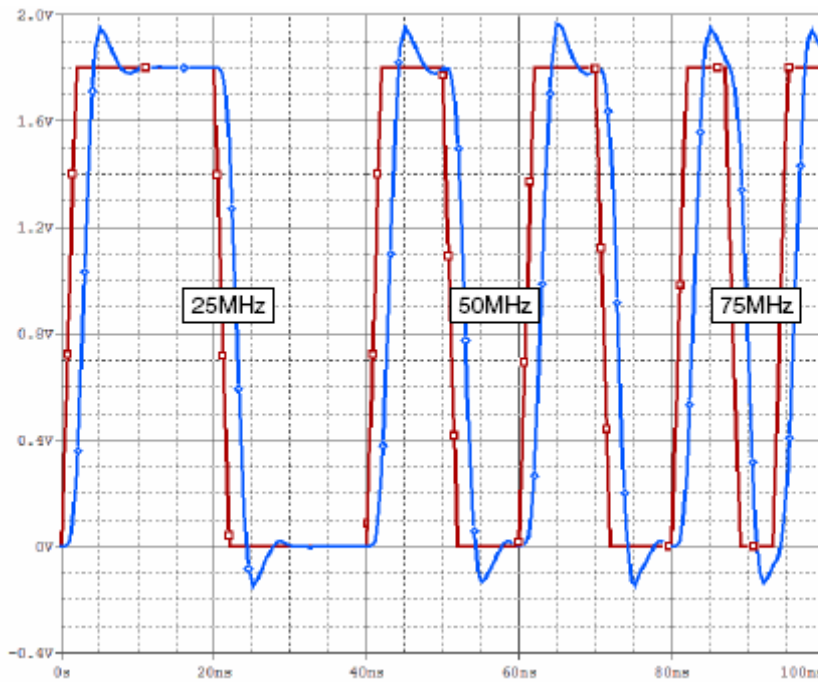


Figure 8. Simulated Transient Response (input signal risetime and falltime = 2 ns, clocked at 25, 50 and 75 MHz, 15 Ω Source Resistance, 5 pF Load)

APPLICATION INFORMATION

Table 5. PRINTED CIRCUIT BOARD RECOMMENDATIONS

Parameter	Value
Pad Size on PCB	0.240 mm
Pad Shape	Round
Pad Definition	Non-Solder Mask defined pads
Solder Mask Opening	0.290 mm Round
Solder Stencil Thickness	0.125 – 0.150 mm
Solder Stencil Aperture Opening (laser cut, 5% tapered walls)	0.300 mm Round
Solder Flux Ratio	50/50 by volume
Solder Paste Type	No Clean
Pad Protective Finish	OSP (Entek Cu Plus 106A)
Tolerance – Edge To Corner Ball	±50 µm
Solder Ball Side Coplanarity	±20 µm
Maximum Dwell Time Above Liquidous	60 seconds
Maximum Soldering Temperature for Lead-free Devices using a Lead-free Solder Paste	260°C

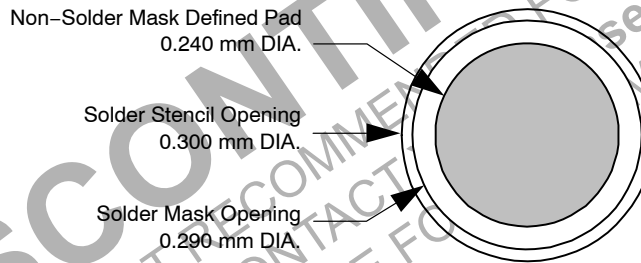


Figure 9. Recommended Non-Solder Mask Defined Pad Illustration

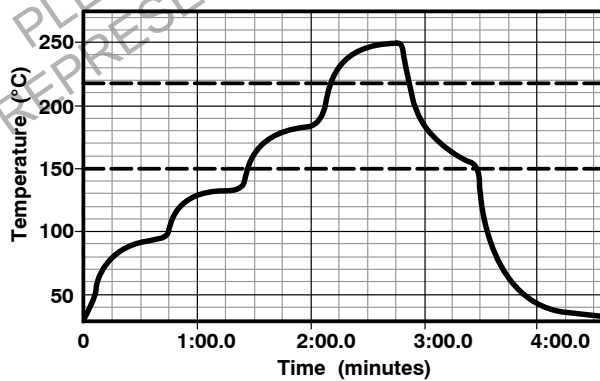


Figure 10. Lead-free (SnAgCu) Solder Ball Reflow Profile



# MECHANICAL CASE OUTLINE

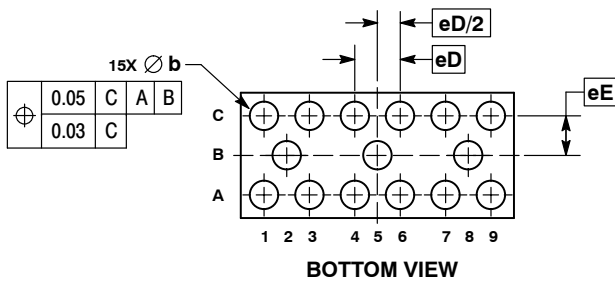
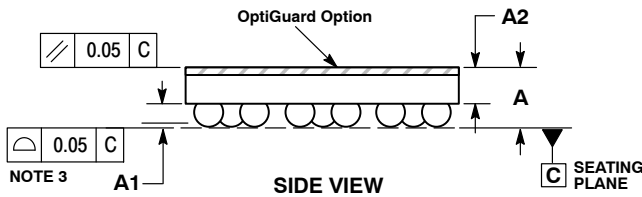
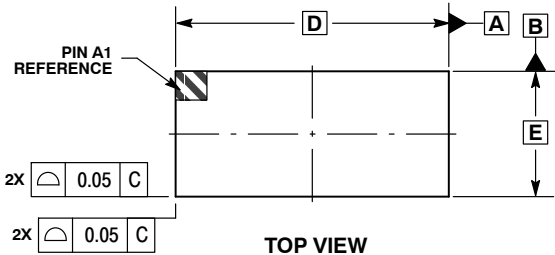
## PACKAGE DIMENSIONS



SCALE 4:1

**WLCSP15, 3.01x1.38**  
CASE 567BT-01  
ISSUE O

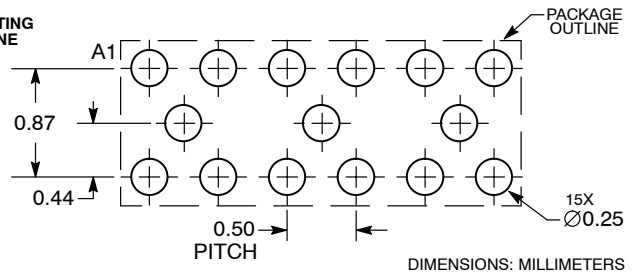
DATE 26 JUL 2010



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.72
A1	0.21	0.27
A2	0.42 REF	
b	0.29	0.35
D	3.01 BSC	
E	1.38 BSC	
eD	0.50 BSC	
eE	0.435 BSC	

### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

<b>DOCUMENT NUMBER:</b>	<b>98AON49827E</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>WLCSP15, 3.01X1.38</b>	<b>PAGE 1 OF 1</b>

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

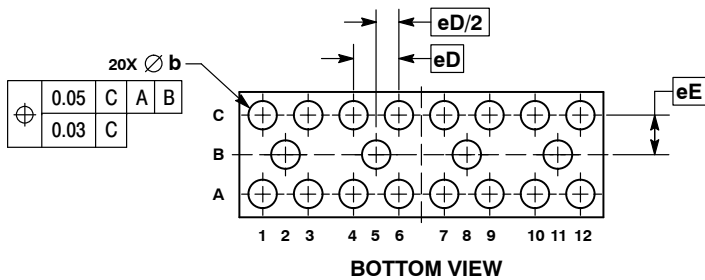
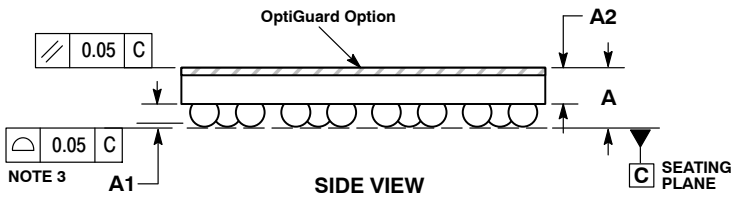
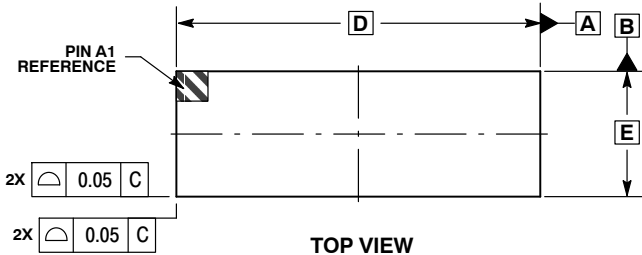
ON Semiconductor®



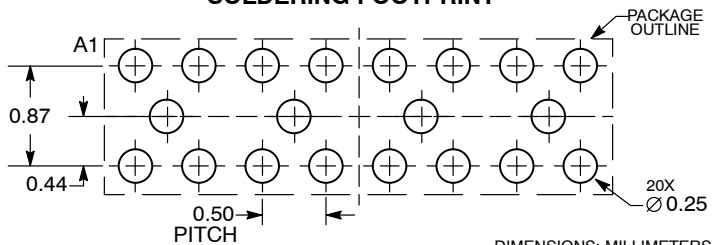
**WLCSP20, 4.01x1.38**  
CASE 567CL-01  
ISSUE O

DATE 26 JUL 2010

SCALE 4:1



### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.72
A1	0.21	0.27
A2	0.42 REF	
b	0.29	0.35
D	4.01 BSC	
E	1.38 BSC	
eD	0.50 BSC	
eE	0.435 BSC	

<b>DOCUMENT NUMBER:</b>	<b>98AON50484E</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>WLCSP20, 4.01X1.38</b>	<b>PAGE 1 OF 1</b>

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

**onsemi**, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## ADDITIONAL INFORMATION

### TECHNICAL PUBLICATIONS:

Technical Library: [www.onsemi.com/design/resources/technical-documentation](http://www.onsemi.com/design/resources/technical-documentation)  
onsemi Website: [www.onsemi.com](http://www.onsemi.com)

### ONLINE SUPPORT: [www.onsemi.com/support](http://www.onsemi.com/support)

For additional information, please contact your local Sales Representative at [www.onsemi.com/support/sales](http://www.onsemi.com/support/sales)